

Electronic Patent Application Fee Transmittal

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|---|---|-----------------|---------------|-----------------------------|
| Application Number: | 10593152 | | | |
| Filing Date: | 18-Sep-2006 | | | |
| Title of Invention: | Electrodeposited Copper Foil with Carrier Foil on which a Resin Layer for Forming Insulating Layer is Formed, Copper-Clad Laminate, Printed Wiring Board, Method for Manufacturing Multilayer Copper-Clad Laminate, and Method for Manufacturing Printed Wiring Board | | | |
| First Named Inventor/Applicant Name: | Seiji Nagatani | | | |
| Filer: | Stephen M. Roylance/Annette Limberg | | | |
| Attorney Docket Number: | 3209-124 | | | |
| Filed as Large Entity | | | | |
| U.S. National Stage under 35 USC 371 Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |
| Extension - 1 month with \$0 paid | 1251 | 1 | 130 | 130 |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|---|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Submission- Information Disclosure Stmt | 1806 | 1 | 180 | 180 |
| Total in USD (\$) | | | | 310 |